

**SPECIFICATION
OF
LCD MODULE**

MODULE NO.: HL070T62-05

Customer Approval:

☐ **Accept**

☐ **Reject**

	SIGNATURE	DATE
PREPARED BY		
CHECKED BY		
APPROVED BY		

DOCUMENT REVISION HISTORY

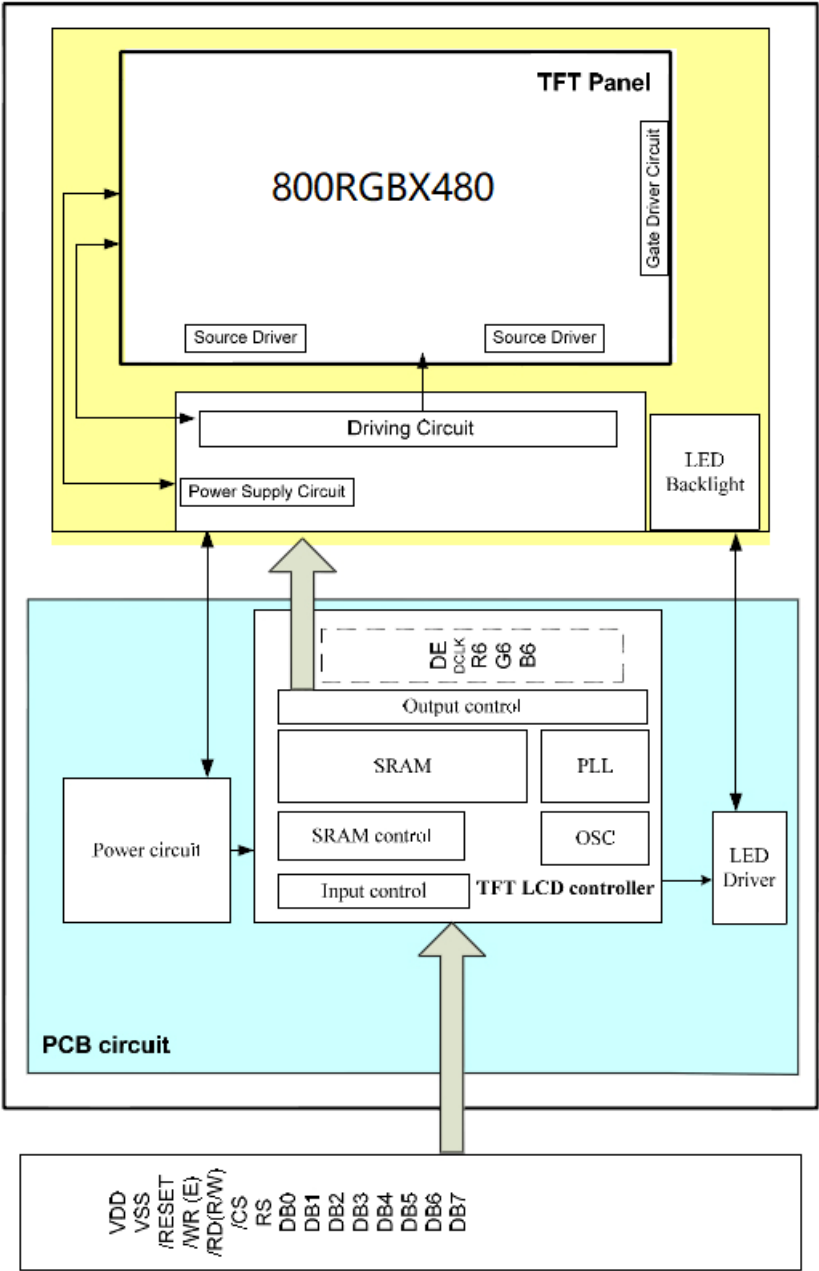
Sample Version	Doc. Version	DATE	DESCRIPTION	CHECKED BY
	A0	2024-07-2	First Release.	
	A1	2024-7-6	Add control IC	

1. MECHANICAL SPECIFICATIONS:

ITEM	SPECIFICATION	UNIT
OUTLINE DIMENSIONS	181.2(W) X100.0(H) X4.75(D)	mm
ACTIVE AREA	154.08X85.92	mm
DISPLAY SIZE	7	inch
PIXEL PITCH	0.1926X0.1926	mm
NUMBER OF DOTS	800* (RGB) *480	-
INTERFACE	MCU	-
CONTROL IC	SSD1963	
LCD TYPE	TFT(262K) TRANSMISSIVE	-
BACKLIGHT TYPE	LED White	-
VIEWING DIRECTION	FREE	-

***See attached drawing for details.**

2.BLOCK DIAGRAM:



3.DIMENSIONAL

Display Type	7.0TFT-LCD(Normally White Transmissive)
Display Resolution	800(H)*3(RGB)*480(V)
Interface	MCU
Logic Voltage	3.3V
LCD Driving Voltage	TBD
Operation Temperature	-20°C TO 70°C
Storage Temperature	-30°C TO 80°C
Remark	

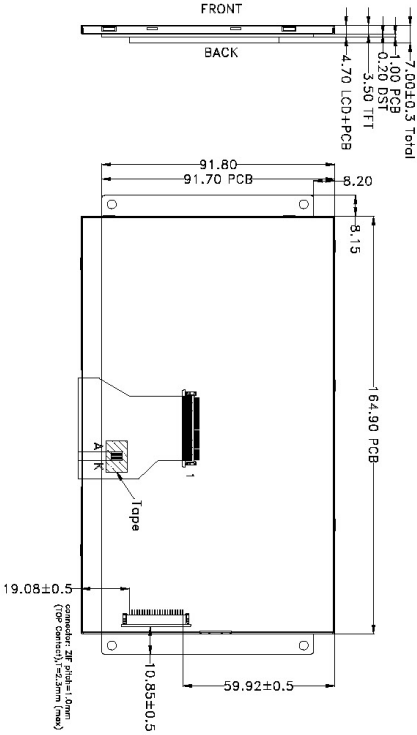
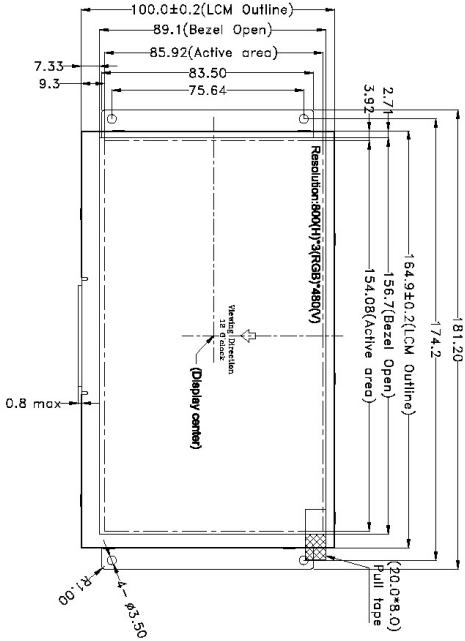
1.0	First version
MARK REV	CONTENTS MODIFIED

TITLE: LCM DIMENSION		REV: 2.0		SCALE: -	
DESIGN		CHECKED		PROJECTION	
APPROVED		DATE			

HL 海罗光电有限公司
Hello Lighting co.,LTD

HL070T62-05

FPC ASSIGNMENT:									
1	GND	11	DB4	21	NCX1				
2	VDDSV	12	DB5	22	NCY1				
3	BL_EN	13	DB6	23					
4	RS	14	DB7	24					
5	WR	15	CS	25					
6	RD	16	RESET	26					
7	DB0	17	NC	27					
8	DB1	18	NCAR	28					
9	DB2	19	DISP ON	29					
10	DB3	20	NCYD	30					



4. PIN DESCRIPTION:

Pin No	Pin Name	I/O	Description
1	GND	P	Power ground
2	VDD5V	P	Power supply, +3.3V
3	BL_EN	P	Power ground
4	RS	IO	Data/index selection
5	WR	IO	Write signal
6	RD	IO	Read signal
7	DB0	IO	Data bus
8	DB1	IO	
9	DB2	IO	
10	DB3	IO	
11	DB4	IO	
12	DB5	IO	
13	DB6	IO	
14	DB7	IO	
15	CS	P	Chip select
16	RESET	I	Global reset
17	NC	I	No connection
18	NC/XR	-I	No connection/ touch right
19	DISP_ON	I	Display on/off
20	NC/YD	I	No connection/ touch bottom
21	NC/XL	P	No connection/ touch left
22	NC/YU	-	No connection/ touch uppon

5. MAXIMUM ABSOLTE LIMIT:

Item	Symbol	Value	Unit
Power supply voltage for logic	V_{DD}	-0.3~6	V
Input voltage	V_{in}	$V_{DD}+0.3$	V
Operating temperature	T_{opr}	-20 to 70	°C
Storage temperature	T_{stg}	-30 to 80	°C

Note: Note1: Absolute maximum rating is the limit value beyond which the IC maybe broken.

They do not assure operations.

Note2: Background color changes slightly depending on ambient temperature. This Phenomenon is reversible.

$T_a \leq 70^{\circ}\text{C}$: 75%RH max

$T_a > 70^{\circ}\text{C}$: absolute humidity must be lower than the humidity of 75%RH at 70°C

Note3: T_a at -30°C will be <48hrs, at 80°C will be <120hrs

6.ELECTRICAL CHARACTERISTICS

6-1 DC Characteristics ($T_a=25^{\circ}\text{C}$)

Item	Symbol	Min	Type	Max	Unit	Test condition
voltage for LCM	V_{CC}	4.5	5	5.5	V	-
Supply current	I_{DD}	-	TBD	-	mA	$V_{DD}=3.3\text{V}, T_a=25^{\circ}\text{C}$
Input voltage	V_{IH}	0.7VDD	-	VDD	V	-
	V_{IL}	0	-	0.3VDD	V	
Input leakage current	I_{IL}	-1.0	-	1.0	μA	$V_{IN}=V_{DD}$ or V_{SS}

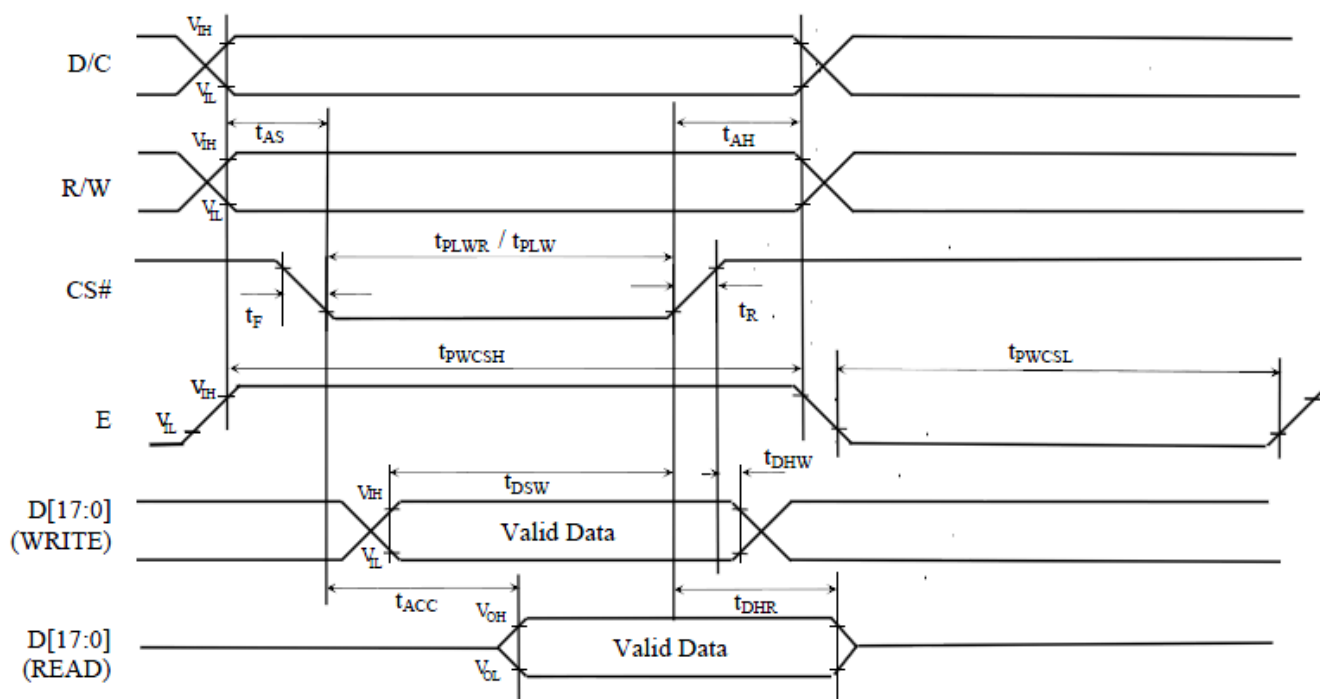
7. TIMING CHARACTERISTICS

7-1 parallel 6800 timing characteristics

Parallel 6800 interface timing, use /CS as clock

Symbol	Parameter	Min	Typ	Max	Unit
f_{MCLK}	System Clock Frequency*	1	-	110	MHz
t_{MCLK}	System Clock Period*	$1/f_{MCLK}$	-	-	ns
t_{PWCSH}	Control Pulse High Width Write Read	13 30	$1.5 * t_{MCLK}$ $3.5 * t_{MCLK}$	-	ns
t_{PWCSL}	Control Pulse Low Width Write (next write cycle) Write (next read cycle) Read	13 80 80	$1.5 * t_{MCLK}$ $9 * t_{MCLK}$ $9 * t_{MCLK}$	-	ns
t_{AS}	Address Setup Time	2	-	-	ns
t_{AH}	Address Hold Time	2	-	-	ns
t_{DSW}	Data Setup Time	4	-	-	ns
t_{DHW}	Data Hold Time	1	-	-	ns
t_{PLW}	Write Low Time	14	-	-	ns
t_{PHW}	Write High Time	14	-	-	ns
t_{PLWR}	Read Low Time	38	-	-	ns
t_{ACC}	Data Access Time	32	-	-	ns
t_{DHR}	Output Hold time	1	-	-	ns
t_R	Rise Time	-	-	0.5	ns
t_F	Fall Time	-	-	0.5	ns

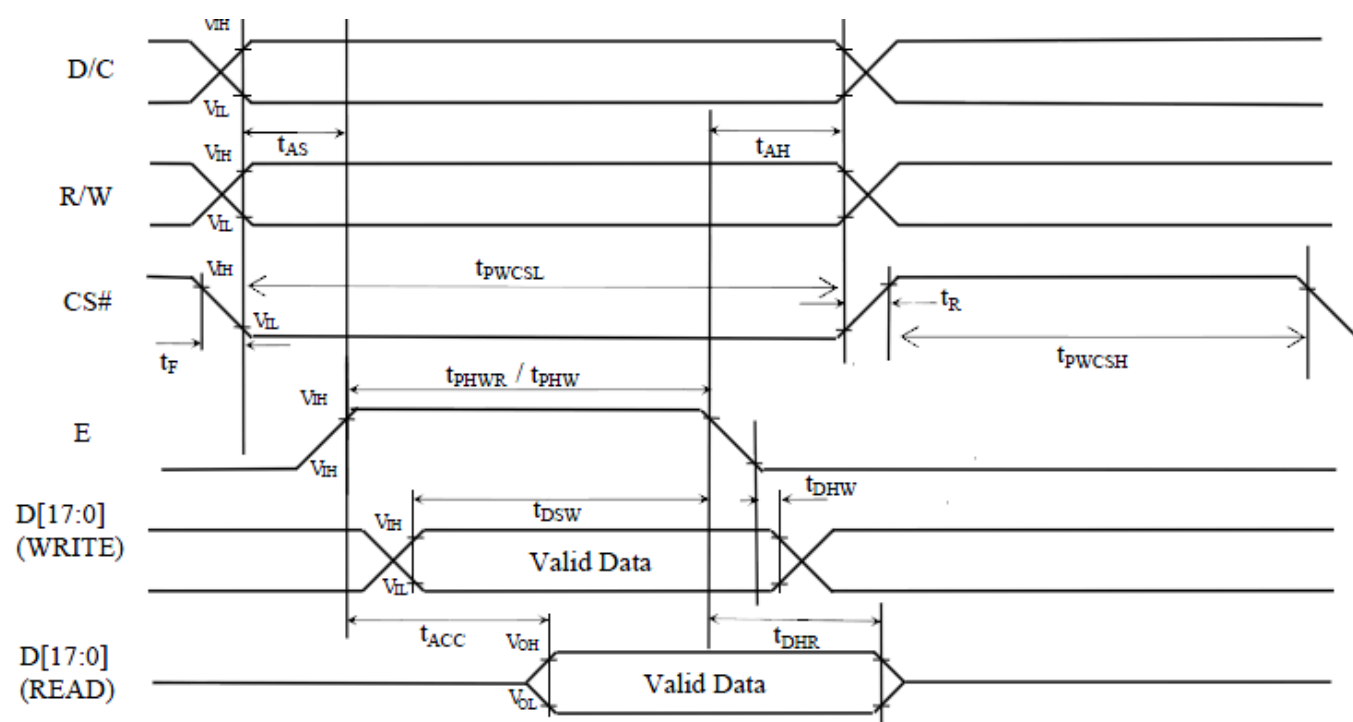
* System Clock denotes external input clock (PLL-bypass) or internal generated clock (PLL-enabled)



Parallel 6800 interface timing, use E as clock

Symbol	Parameter	Min	Typ	Max	Unit
f_{MCLK}	System Clock Frequency*	1	-	110	MHz
t_{MCLK}	System Clock Period*	$1/f_{MCLK}$	-	-	ns
t_{PWCSH}	Control Pulse Low Width	13	$1.5 * t_{MCLK}$	-	ns
	Write (next write cycle)	80	$9 * t_{MCLK}$	-	
	Read (next read cycle)	80	$9 * t_{MCLK}$	-	
t_{PWCSL}	Control Pulse High Width	13	$1.5 * t_{MCLK}$	-	ns
	Write	30	$3.5 * t_{MCLK}$	-	
t_{AS}	Address Setup Time	2	-	-	ns
t_{AH}	Address Hold Time	2	-	-	ns
t_{DSW}	Data Setup Time	4	-	-	ns
t_{DHW}	Data Hold Time	1	-	-	ns
t_{PLW}	Write Low Time	14	-	-	ns
t_{PHW}	Write High Time	14	-	-	ns
t_{PLWR}	Read Low Time	38	-	-	ns
t_{ACC}	Data Access Time	32	-	-	ns
t_{DHR}	Output Hold time	1	-	-	ns
t_R	Rise Time	-	-	0.5	ns
t_F	Fall Time	-	-	0.5	ns

* System Clock denotes external input clock (PLL-bypass) or internal generated clock (PLL-enabled)

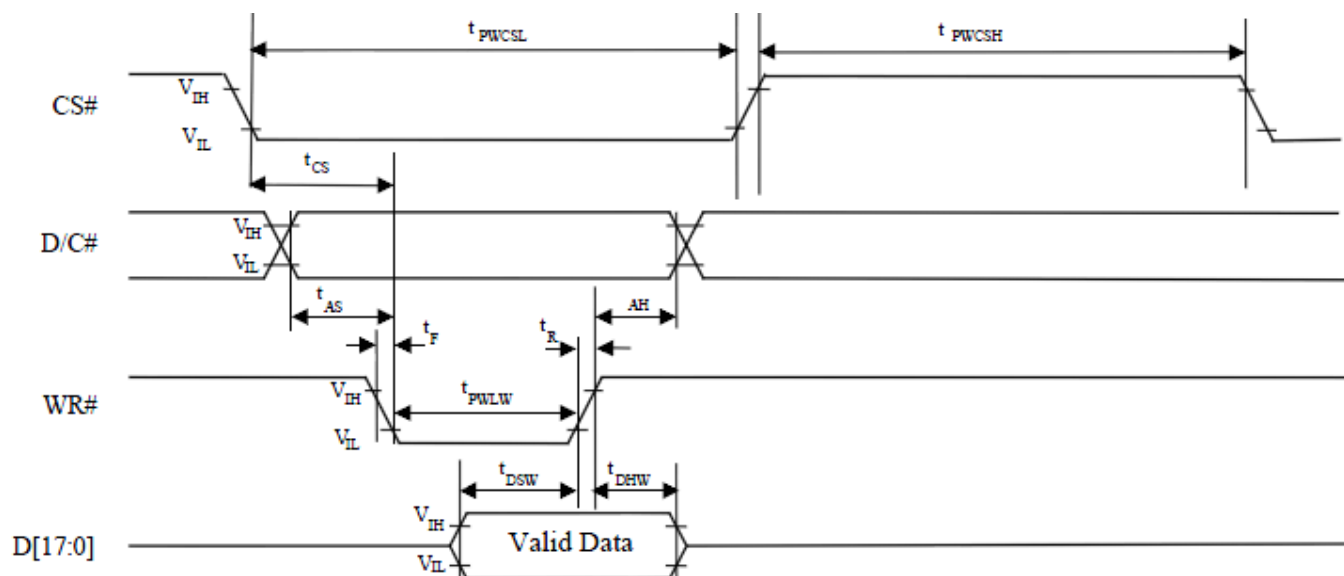


7-2 Parallel 8080 timing characteristics

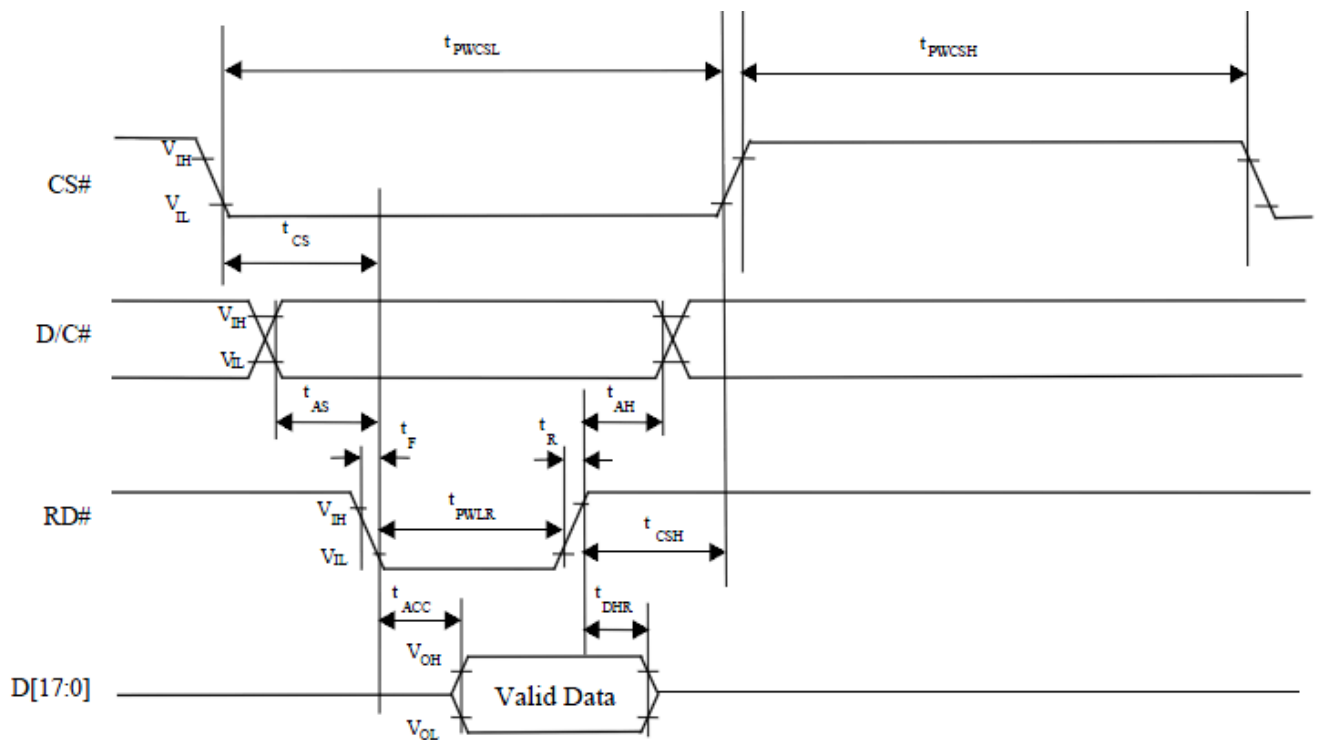
Symbol	Parameter	Min	Typ	Max	Unit
f_{MCLK}	System Clock Frequency*	1	-	110	MHz
t_{MCLK}	System Clock Period*	$1/f_{MCLK}$	-	-	ns
t_{PWCSL}	Control Pulse High Width Write	13	$1.5 * t_{MCLK}$	-	ns
	Read	30	$3.5 * t_{MCLK}$	-	ns
t_{PWCSH}	Control Pulse Low Width Write (next write cycle)	13	$1.5 * t_{MCLK}$	-	ns
	Write (next read cycle)	80	$9 * t_{MCLK}$	-	ns
	Read	80	$9 * t_{MCLK}$	-	ns
t_{AS}	Address Setup Time	1	-	-	ns
t_{AH}	Address Hold Time	2	-	-	ns
t_{DSW}	Write Data Setup Time	4	-	-	ns
t_{DHW}	Write Data Hold Time	1	-	-	ns
t_{PWLW}	Write Low Time	12	-	-	ns
t_{DHR}	Read Data Hold Time	1	-	-	ns
t_{ACC}	Access Time	32	-	-	ns
t_{PWLr}	Read Low Time	36	-	-	ns
t_R	Rise Time	-	-	0.5	ns
t_F	Fall Time	-	-	0.5	ns
t_{CS}	Chip select setup time	2	-	-	ns
t_{CSH}	Chip select hold time to read signal	3	-	-	ns

* System Clock denotes external input clock (PLL-bypass) or internal generated clock (PLL-enabled)

Parallel 8080 interface timing, write cycle



Parallel 8080 interface timing, read cycle



7-3 data transfer order setting

Interface	Cycle	D[23]	D[22]	D[21]	D[20]	D[19]	D[18]	D[17]	D[16]	D[15]	D[14]	D[13]	D[12]	D[11]	D[10]	D[9]	D[8]	D[7]	D[6]	D[5]	D[4]	D[3]	D[2]	D[1]	D[0]	
24 bits	1 st	R7	R6	R5	R4	R3	R2	R1	R0	G7	G6	G5	G4	G3	G2	G1	G0	B7	B6	B5	B4	B3	B2	B1	B0	
18 bits	1 st							R5	R4	R3	R2	R1	R0	G5	G4	G3	G2	G1	G0	B5	B4	B3	B2	B1	B0	
16 bits (565 format)	1 st									R5	R4	R3	R2	R1	G5	G4	G3	G2	G1	G0	B5	B4	B3	B2	B1	
16 bits	1 st									R7	R6	R5	R4	R3	R2	R1	R0	G7	G6	G5	G4	G3	G2	G1	G0	
	2 nd									B7	B6	B5	B4	B3	B2	B1	B0	R7	R6	R5	R4	R3	R2	R1	R0	
	3 rd									G7	G6	G5	G4	G3	G2	G1	G0	B7	B6	B5	B4	B3	B2	B1	B0	
12 bits	1 st													R7	R6	R5	R4	R3	R2	R1	R0	G7	G6	G5	G4	
	2 nd													G3	G2	G1	G0	B7	B6	B5	B4	B3	B2	B1	B0	
9 bits	1 st																R5	R4	R3	R2	R1	R0	G5	G4	G3	
	2 nd																G2	G1	G0	B5	B4	B3	B2	B1	B0	
8 bits	1 st																	R7	R6	R5	R4	R3	R2	R1	R0	
	2 nd																	G7	G6	G5	G4	G3	G2	G1	G0	
	3 rd																	B7	B6	B5	B4	B3	B2	B1	B0	

7-4 command table

Hex	Code	Command Description
0x00	nop No operation	
0x01	soft_reset	Software Reset
0x0A	get_power_mode	Get the current power mode
0x0B	get_address_mode	Get the frame buffer to the display panel read order
0x0C	Reserved	Reserved
0x0D	get_display_mode	The SSD1963 returns the Display Image Mode.
0x0E	get_tear_effect_status	Get the Tear Effect status
0x0F	Reserved	Reserved

0x10	enter_sleep_mode	Turn off the panel. This command will pull low the GPIO0. If GPIO0 is configured as normal GPIO or LCD miscellaneous signal with command set_gpio_conf, this command will be ignored.
0x11	exit_sleep_mode	Turn on the panel. This command will pull high the GPIO0. If GPIO0 is configured as normal GPIO or LCD miscellaneous signal with command set_gpio_conf, this command will be ignored.
0x12	enter_partial_mode	Part of the display area is used for image display.
0x13	enter_normal_mode	The whole display area is used for image display.
0x20	exit_invert_mode	Displayed image colors are not inverted.
0x21	enter_invert_mode	Displayed image colors are inverted.
0x26	set_gamma_curve	Selects the gamma curve used by the display panel.
0x28	set_display_off	Blanks the display panel
0x29	set_display_on	Show the image on the display panel
0x2A	set_column_address	Set the column address
0x2B	set_page_address	Set the page address
0x2C	write_memory_start	Transfer image information from the host processor interface to the SSD1963 starting at the location provided by set_column_address and set_page_address
0x2E	read_memory_start	Transfer image data from the SSD1963 to the host processor interface starting at the location provided by set_column_address and set_page_address
0x30	set_partial_area	Defines the partial display area on the display panel
0x33	set_scroll_area	Defines the vertical scrolling and fixed area on display area
0x34	set_tear_off	Synchronization information is not sent from the SSD1963 to the host processor
0x35	set_tear_on	Synchronization information is sent from the SSD1963 to the host processor at the start of VFP
0x36	set_address_mode	Set the read order from frame buffer to the display panel
0x37	set_scroll_start	Defines the vertical scrolling starting point
0x38	exit_idle_mode	Full color depth is used for the display panel
0x39	enter_idle_mode	Reduce color depth is used on the display panel.
0x3A	Reserved	Reserved

0x3C	write_memory_continue	Transfer image information from the host processor interface to the SSD1963 from the last written location
0x3E	read_memory_continue	Read image data from the SSD1963 continuing after the last read_memory_continue or read_memory_start
0x44	set_tear_scanline	Synchronization information is sent from the SSD1963 to the host processor when the display panel refresh reaches the provided scanline
0x45	get_scanline	Get the current scan line
0xA1	read_ddb	Read the DDB from the provided location
0xA8	Reserved	Reserved
0xB0	set_lcd_mode	Set the LCD panel mode and resolution
0xB1	get_lcd_mode	Get the current LCD panel mode, pad strength and resolution
0xB4	set_hori_period	Set front porch
0xB5	get_hori_period	Get current front porch settings
0xB6	set_vert_period	Set the vertical blanking interval between last scan line and
		next LFRAME pulse
0xB7	get_vert_period	Set the vertical blanking interval between last scan line and
		next LFRAME pulse
0xB8	set_gpio_conf	Set the GPIO configuration. If the GPIO is not used for LCD,
		set the direction. Otherwise, they are toggled with LCD
		signals.
0xB9	get_gpio_conf	Get the current GPIO configuration
0xBA	set_gpio_value	Set GPIO value for GPIO configured as output
0xBB	get_gpio_status	Read current GPIO status. If the individual GPIO was configured as input, the value is the status of the corresponding pin. Otherwise, it is the programmed value.
0xBC	set_post_proc	Set the image post processor
0xBD	get_post_proc	Set the image post processor
0xBE	set_pwm_conf	Set the image post processor
0xBF	get_pwm_conf	Set the image post processor
0xC0	set_lcd_gen0	Set the rise, fall, period and toggling properties of LCD signal generator 0
0xC1	get_lcd_gen0	Get the current settings of LCD signal generator 0
0xC2	set_lcd_gen1	Set the rise, fall, period and toggling properties of LCD signal generator 1
0xC3	get_lcd_gen1	Get the current settings of LCD signal generator 1

0xC4	set_lcd_gen2	Set the rise, fall, period and toggling properties of LCD signal generator 2
0xC5	get_lcd_gen2	Get the current settings of LCD signal generator 2
0xC6	set_lcd_gen3	Set the rise, fall, period and toggling properties of LCD signal generator 3
0xC7	get_lcd_gen3	Get the current settings of LCD signal generator 3
0xC8	set_gpio0_rop	Set the GPIO0 with respect to the LCD signal generators using ROP operation. No effect if the GPIO0 is configured as general GPIO.
0xC9	get_gpio0_rop	Get the GPIO0 properties with respect to the LCD signal generators.
0xCA	set_gpio1_rop	Set the GPIO1 with respect to the LCD signal generators
		using ROP operation. No effect if the GPIO1 is configured as general GPIO.
0xCB	get_gpio1_rop	Get the GPIO1 properties with respect to the LCD signal generators.
0xCC	set_gpio2_rop	Set the GPIO2 with respect to the LCD signal generators using ROP operation. No effect if the GPIO2 is configured as general GPIO.
0xCD	get_gpio2_rop	Get the GPIO2 properties with respect to the LCD signal generators.
0xCE	set_gpio3_rop	Set the GPIO3 with respect to the LCD signal generators using ROP operation. No effect if the GPIO3 is configured as general GPIO.
0xCF	get_gpio3_rop	Get the GPIO3 properties with respect to the LCD signal generators.
0xD0	set_dbc_conf	Set the dynamic back light configuration
0xD1	get_dbc_conf	Get the current dynamic back light configuration
0xD4	set_dbc_th	Set the threshold for each level of power saving
0xD5	get_dbc_th	Get the threshold for each level of power saving
0xE0	set_pll	Start the PLL. Before the start, the system was operated with the crystal oscillator or clock input
0xE2	set_pll_mn	Set the PLL
0xE3	get_pll_mn	Get the PLL settings
0xE4	get_pll_status	Get the current PLL status
0xE5	set_deep_sleep	Set deep sleep mode
0xE6	set_lshift_freq	Set the LSHIFT (pixel clock) frequency
0xE7	get_lshift_freq	Get current LSHIFT (pixel clock) frequency setting
0xE8	Reserved	Reserved

0xE9	Reserved	Reserved
0xF0	set_pixel_data_interface	Set the pixel data format of the parallel host processor interface
0xF1	get_pixel_data_interface	Get the current pixel data format settings
0xFF	Reserved	Reserved

8. OPTICAL CHARACTERISTICS:

Driving the backlight

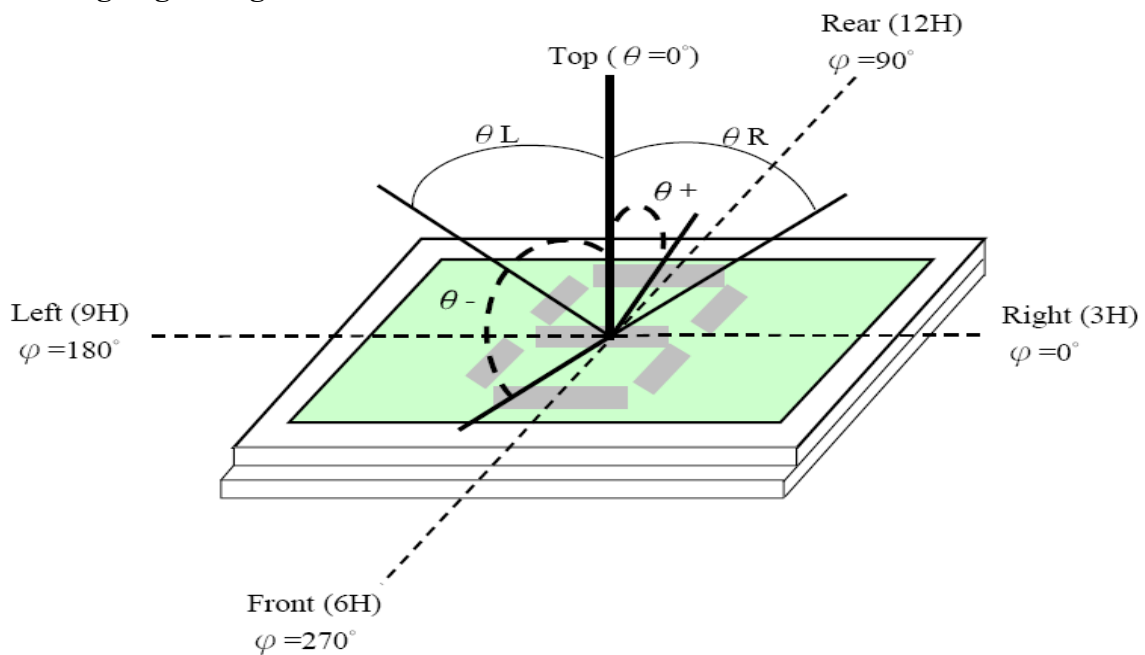
No.	ITEM	Symbol	Conditions	Specification			Unit	Note
				Min	Typ	Max		
1	Response Time	Tr+Tf	25°C	-	20	36	Ms	(1)(2)
2	Contrast Rate	Cr	$\theta=0$, Normal viewing angle	600	800	-	-	(1)(3)
3	Viewing Angle	Hor.	θL	CR>10	60	-	Deg	-
			θR		60	-		
		Ver.	$\theta +$		70	-		
			$\theta -$		60	-		
4	Chromaticiry	White	x	Brightness is ON	0.249	0.299	0.349	
			y		0.278	0.328	0.378	
5	luminance	L		400	500		cd/m2	
6	Uniformity	U		80			%	

Measure Conditions:

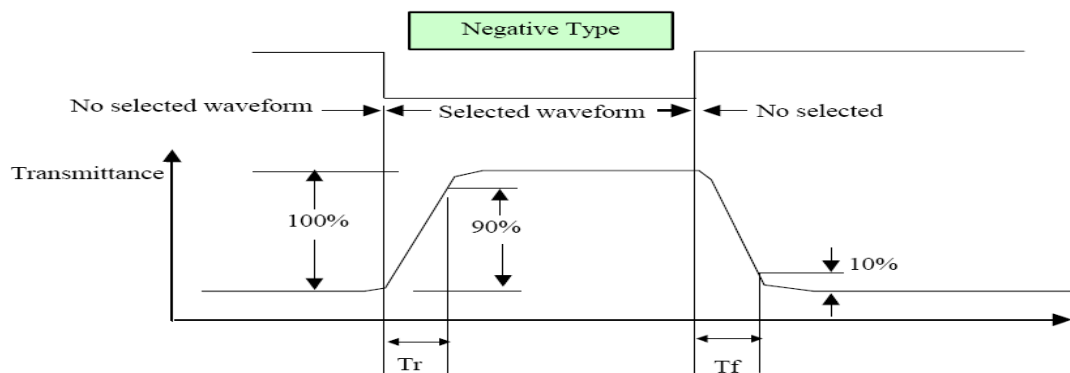
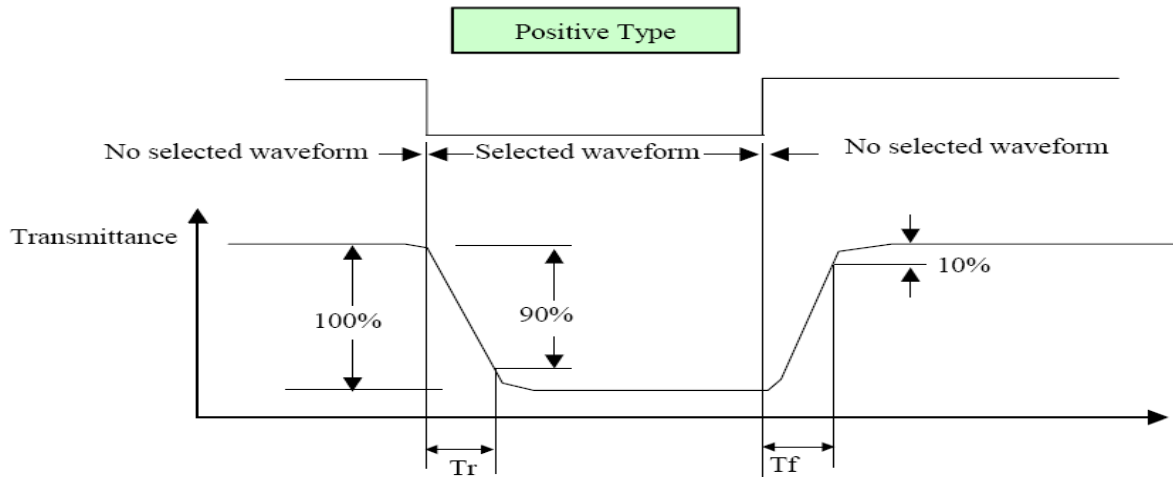
1. Measure surrounding : dark room;
2. Ambient temperature: $25\pm 2^\circ\text{C}$;
3. 30min.warm-up time.

Note Definition:

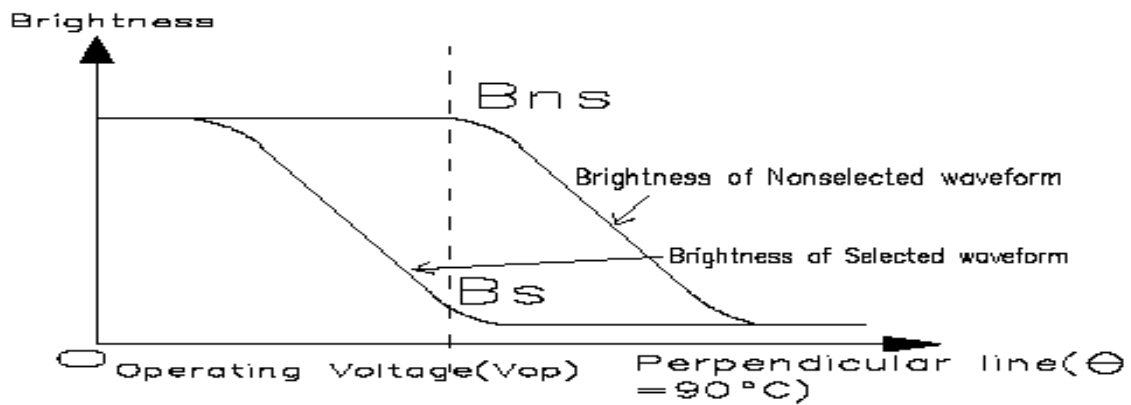
Note(1)Viewing angle range:



Note (2) Response Time:

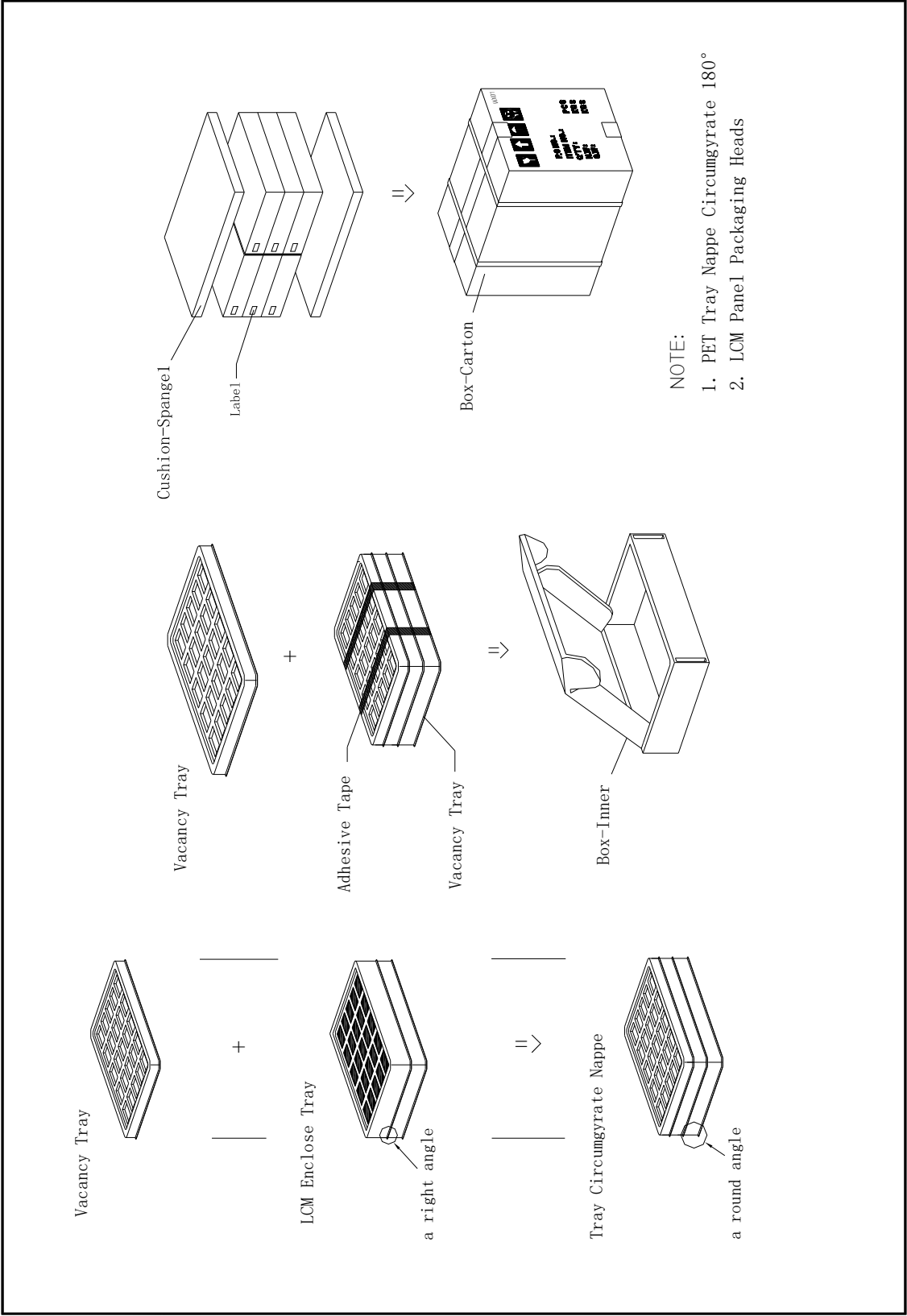


Note(3) Contrast Ratio Definition:



$$\text{Contrast Ratio (Cr)} = \frac{\text{Luminance with all pixel white}}{\text{Luminance with all pixel black}}$$

9.PACKAGE.



10. STANDARD SPECIFICATION FOR RELIABILITY:

Item	Condition		Time (hrs)	Assessment
High temp. Storage	80°C		120	No abnormalities in functions and appearance
High temp. Operating	70°C		120	
Low temp. Storage	-30°C		120	
Low temp. Operating	-20°C		120	
Humidity	40°C/ 90%RH		120	
Thermal Shock Temp. Cycle	-30°C ← →70°C (0.5hour ← → 0.5 hour)		10cycles	
ESD Testing	HBM:	±8KV		330Ω/150PF
	MM:	±200V		200PF/0Ω

Functions, performance, appearance, etc. shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage conditions room temperature ($25\pm10^{\circ}\text{C}$), normal humidity ($45\pm20\%$ RH), and in area not exposed to direct sun light. (Life time of backlight, please refer to Data about backlight.)

Testing Conditions and Inspection Criteria:

For the final test the testing sample must be stored at room temperature for 24 hours, after the tests listed in up Table, Standard specifications for Reliability have been executed in order to ensure stability.

Item	Test Model	In section Criteria
Current Consumption	Refer To Specification	The current consumption should conform to the product specification.
Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
Appearance	Visual inspection	Defect free.

11.SPECIFICATION OF QUALITY ASSURANCE:

11.1 Purpose

This standard for Quality Assurance should affirm the quality of LCD Module products to supply to purchaser.

11.2 Standard for Quality Test

a. Inspection:

Before delivering, the supplier should take the following tests, and affirm the quality of product.

b. Electro-Optical Characteristics:

According to the individual specification to test the product.

c. Test of Appearance Characteristics:

According to the individual specification to test the product.

d. Test of Reliability Characteristics:

According to the definition of reliability on the specification for testing products.

e. Delivery Test:

Before delivering, the supplier should take the delivery test.

(i) Test method: According to MIL-STD105E.General Inspection Level II take a single time.

(ii) The defects classify of AQL as following:

Major defect: AQL = 0.65

Minor defect: AQL = 2.5

Total defects: AQL = 2.5

11.3. Nonconforming Analysis & Deal With Manners

a. Nonconforming Analysis:

(i) Purchaser should supply the detail data of non- conforming sample and the non- conforming.

(ii) After accepting the detail data from purchaser, the analysis of nonconforming should be finished in two weeks.

(iii) If supplier can not finish analysis on time, must announce purchaser before two weeks.

b. Disposition of nonconforming:

(i) If find any product defect of supplier during assembly time, supplier must change the good product for every defect after recognition.

(ii) Both supplier and customer should analyze the reason and discuss the disposition of nonconforming when the reason of nonconforming is not sure.

11.4. Agreement items

Both sides should discuss together when the following problems happen.

a. There is any problem of standard of quality assurance, and both sides think that it must be modified.

b. There is any argument item which does not record in the standard of quality assurance.

c. Any other special problem.

11.5 Standard of The Product Appearance Test

a. Manner of appearance test: This specification should be applied for both light on and off situation.

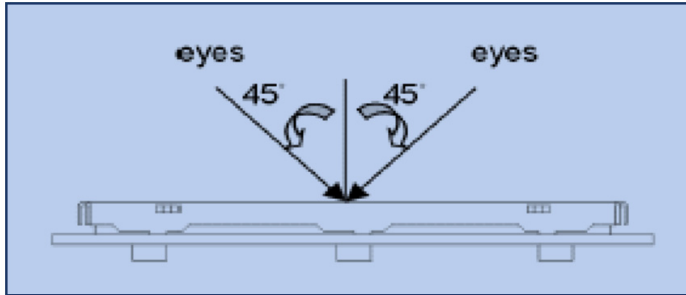
(i) The test must be under 20W × 2 or 40W fluorescent light, and the distance of view must

be at 30 ± 5 cm.

(ii) When test the model of transmissive product must add the reflective plate.

(iii) The test direction is base on about around 10° of vertical line (Left graph)

(iii) Temperature: $25 \pm 5^\circ\text{C}$ Humidity: $65 \pm 10\% \text{RH}$



(iv) Definition of area (Right graph)

A. Area: Viewing area. B. Area: Out of viewing area. (Outside viewing area)

b. Basic principle:

(i) It will accord to the AQL when the standard can not be described.

(ii) The sample of the lowest acceptable quality level must be discussed by both supplier and customer when any dispute happened.

(iii) Must add new item on time when it is necessary.

c. Standard of inspection: (Unit: mm)

Allowable limits defined in follow Dot defect Table should be met for each white, black, R, G, B raster. The limits apply to the entire area. Missing white in 60% or more of typical (one color, R or G or B) pixel aperture is defined as a bright defect, less than 60% is acceptable. Black spot in 60% or more of typical pixel aperture is defined as a dark defect, less than 60% is acceptable.

Dot defect table:

Item		White dot defect	Black dot defect	Total
1	Defect counts	3	3	3
2	Combined defect Counts	No combined dot defect allowed. Two Single dot defect that within 5mm during each dot defect should be counted as combined dot defect.		

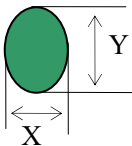
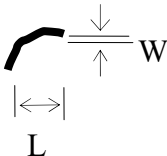
11.6 Inspection specification

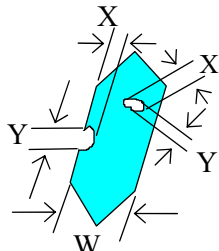
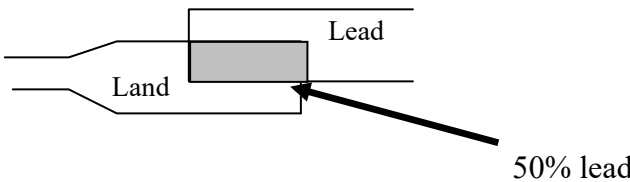
AQL inspection standard

Sampling method: MIL-STD-105E, Level II, single sampling

Classify	Item		Note	AQL	
Major	Display state	Short or open circuit	1	0.65	
		Contrast defect (dim, ghost)			
		LC leakage			
		Flickering			
		No display			
		Wrong viewing direction	2		
		Wrong Back-light	7		
	Non-display	Flat cable or pin reverse	9		
		Wrong or missing component	10		
Minor	Display state	Background color deviation	2	2.5	
		Black spot and dust	3		
		Line defect	4		
		Scratch			
		Rainbow	5		
		Pin hole	6		
	Polarizer	Bubble and foreign material	3		
		Scratch	4		
	PCB,FPC	Scratch	4		
	Soldering	Poor connection	8		
	Wire	Poor connection	9		
	LCD	CHIP OUT	11		

Note on defect classification:

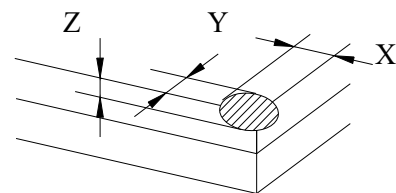
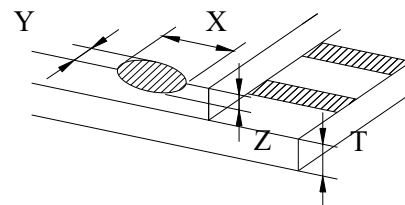
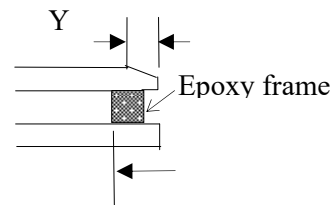
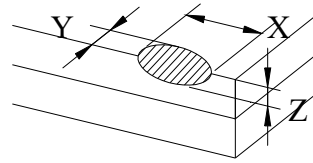
No.	Item	Criterion																				
1	Short or open circuit	Not allow																				
	LC leakage																					
	Flickering																					
	No display																					
	Wrong viewing direction																					
	Wrong Back-light																					
2	Contrast defect	Refer to approval sample																				
	Background color deviation																					
3	Point defect, Black spot, dust (incl. Polarizer) ex.: dirt under polarizer, Pinhole of reflector ,glass scratch, dirt under glass,scratch on polarizer $\phi = (X+Y)/2$	 <table><tr><td>Point</td><td>Acceptable Qty.</td></tr><tr><td>Size</td><td></td></tr><tr><td>$\phi \leq 0.20$</td><td>Disregard</td></tr><tr><td>$0.20 < \phi \leq 0.25$</td><td>3</td></tr><tr><td>$0.25 < \phi \leq 0.30$</td><td>2</td></tr><tr><td>$\phi > 0.30$</td><td>0</td></tr></table> Unit: mm	Point	Acceptable Qty.	Size		$\phi \leq 0.20$	Disregard	$0.20 < \phi \leq 0.25$	3	$0.25 < \phi \leq 0.30$	2	$\phi > 0.30$	0								
Point	Acceptable Qty.																					
Size																						
$\phi \leq 0.20$	Disregard																					
$0.20 < \phi \leq 0.25$	3																					
$0.25 < \phi \leq 0.30$	2																					
$\phi > 0.30$	0																					
4	Line defect	 <table><tr><td></td><td>Line</td><td>Acceptable Qty.</td></tr><tr><td>L</td><td>W</td><td></td></tr><tr><td>---</td><td>$0.015 \geq W$</td><td>Disregard</td></tr><tr><td>$3.0 \geq L$</td><td>$0.03 \geq W$</td><td rowspan="2">2</td></tr><tr><td>$2.0 \geq L$</td><td>$0.05 \geq W$</td></tr><tr><td>$1.0 \geq L$</td><td>$0.1 > W$</td><td>1</td></tr><tr><td>---</td><td>$0.05 < W$</td><td>Applied as point defect</td></tr></table> Unit: mm		Line	Acceptable Qty.	L	W		---	$0.015 \geq W$	Disregard	$3.0 \geq L$	$0.03 \geq W$	2	$2.0 \geq L$	$0.05 \geq W$	$1.0 \geq L$	$0.1 > W$	1	---	$0.05 < W$	Applied as point defect
	Line	Acceptable Qty.																				
L	W																					
---	$0.015 \geq W$	Disregard																				
$3.0 \geq L$	$0.03 \geq W$	2																				
$2.0 \geq L$	$0.05 \geq W$																					
$1.0 \geq L$	$0.1 > W$	1																				
---	$0.05 < W$	Applied as point defect																				
5	Rainbow	Not more than two color changes across the viewing area																				

No.	Item	Criterion								
6	Segment pattern W = Segment width $\phi = (X+Y)/2$	(1) Pin hole $\phi < 0.10\text{mm}$ is acceptable.  <table><tr><th>Point Size</th><th>Acceptable Qty</th></tr><tr><td>$\phi \leq 1/4W$</td><td>Disregard</td></tr><tr><td>$1/4W < \phi \leq 1/2W$</td><td>1</td></tr><tr><td>$\phi > 1/2W$</td><td>0</td></tr></table> Unit: mm	Point Size	Acceptable Qty	$\phi \leq 1/4W$	Disregard	$1/4W < \phi \leq 1/2W$	1	$\phi > 1/2W$	0
Point Size	Acceptable Qty									
$\phi \leq 1/4W$	Disregard									
$1/4W < \phi \leq 1/2W$	1									
$\phi > 1/2W$	0									
7	Back-light	(1) The color of backlight should correspond its specification. (2) Not allow flickering								
8	Soldering	(1) Not allow heavy dirty and solder ball on PCB or FPC. (The size of dirty refer to point and dust defect) (2) Over 50% of lead should be soldered on Land. 								
9	Wire	(1) Copper wire should not be rusted (2) Not allow crack on copper wire connection. (3) Not allow reversing the position of the flat cable. (4) Not allow exposed copper wire inside the flat cable.								
10	PCB,FPC	(1) Not allow screw rust or damage. (2) Not allow missing or wrong putting of component.								

11

LCD

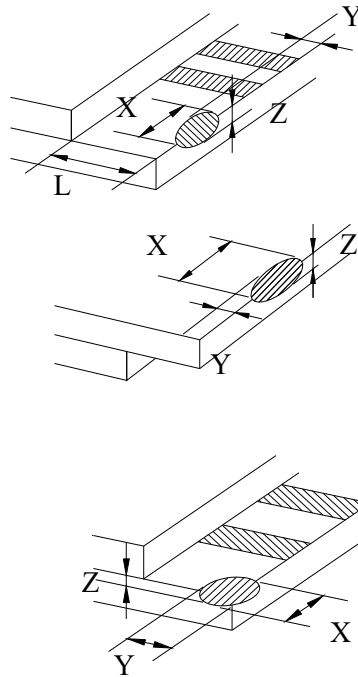
2.1.1 chip on the surface



Note: A: LCD Length

X	Y	Z
$>1/8A$	$\leq 0.3\text{mm}$	$\leq 1/2T$
$\leq 1/8A$	Not enter into epoxy frame	$\leq T$
	Not enter into the inner edge of epoxy	$\leq 1/2T$

2.1.2 Chip on the terminal

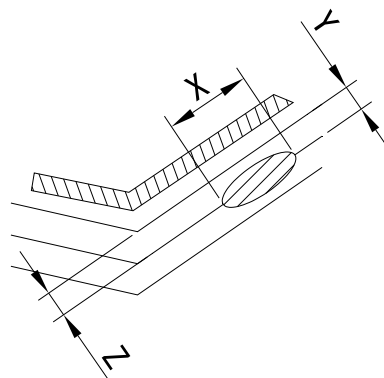


X	Y	Z
$> 1/8A$	$\leq 0.3\text{mm}$	$\leq 1/2T$
$\leq 1/8A$	$\leq 1/2L$	$\leq T$
$\leq 1/8A \text{ \& } \leq 1\text{mm}$	$\leq L$	$\leq T$
$\leq 1/8A \text{ \& } \leq 2\text{mm}$	$\leq L$	$\leq 1/2T$

Note: A: LCD Length.

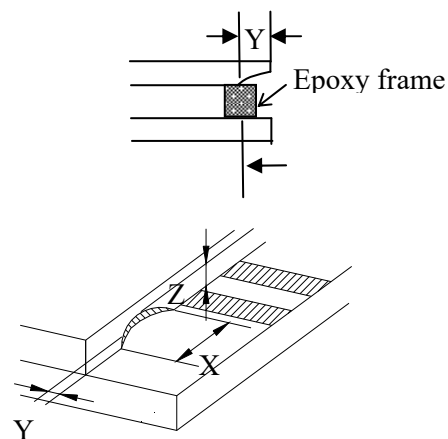
the distance between crack and contact pad must be greater than the width of 1st contact pad.

2.1.3 Chip out on between side



11

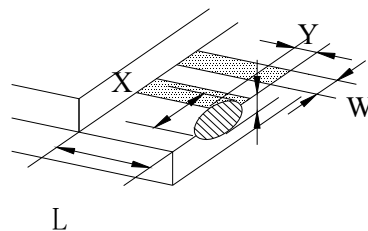
LCD



X	Y	Z
$\leq 1/8A$	Not enter into epoxy frame	$Z \leq 2T$
	Not enter into 1/2 epoxy frame	$Z \leq 1/2T$

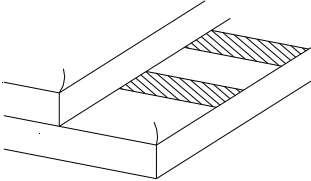
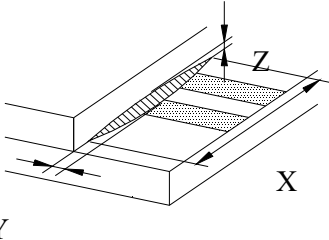
Note: A : LCD Length

2.1.4 including corner chip and side chip



Note: A:LCD Length

X	Y	Z
$>1/8A$	$\leq 1/6L$	$\leq 1/2T$
$\leq 1/8A$	$\leq 1/3L$	
$\leq 1/4W$	$\leq 2/3L$	

11	LCD	2.2 Chip out  1) Chip out is that crackles extend to inner edge. 2) Crackles round epoxy frame will be rejected. 3) Chip out on the terminal will be rejected: $Z=T$ length $>1\text{mm}$ or $Z<T$ length $>2\text{mm}$ 4) The chip out at ITO will be rejected. 2.3 Poor cutting  <table border="1" data-bbox="676 943 1158 1189"> <thead> <tr> <th>X</th><th>Y</th><th>Z</th></tr> </thead> <tbody> <tr> <td>$>1/8$ A</td><td>≤ 0.3</td><td>$\leq 1/2T$</td></tr> <tr> <td>$\leq 1/8$ A</td><td>According to drawing</td><td>$1/2T \leq Z \leq T$</td></tr> </tbody> </table> Note : A: LCD Length.	X	Y	Z	$>1/8$ A	≤ 0.3	$\leq 1/2T$	$\leq 1/8$ A	According to drawing	$1/2T \leq Z \leq T$
X	Y	Z									
$>1/8$ A	≤ 0.3	$\leq 1/2T$									
$\leq 1/8$ A	According to drawing	$1/2T \leq Z \leq T$									
12	SMT	According to the <Acceptable of electronic assemblies> IPC-A-610C class 2 stander. Component missing or function defect are Major defect ,the others are Minor defect.									
Any one out of the specification will be rejected.											

12. GENERAL PRECAUTIONS

(1) Mounting Method

The panel of the LCD Module consists of two thin glass plates with polarizers which easily get damaged since the Module is fixed by utilizing fitting holes in the printed circuit board. Extreme care should be taken when handling the LCD Modules.

(2) Caution of LCD handling & cleaning

When cleaning the display surface, use soft cloth with solvent (recommended below) and wipe lightly.

- Isopropyl alcohol
- Ethyl alcohol
- Trichlorotrifluoroethane

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface. Do not use the following solvent:

- Water
- Ketone
- Aromatics

(3) Caution against static charge

The LCD Module use C-MOS LSI drivers, so we recommend that you connect any unused input terminal to VDD or VSS, do not input any signals before power is turned on. And ground your body, Work/assembly table. And assembly equipment to protect against static electricity.

(4) Packaging

Modules use LCD elements, and must be treated as such. Avoid intense shock and falls from a height.

- To prevent modules from degradation. Do not operate or store them exposed directly to sunshine or high temperature/humidity.

(5) Caution for operation

- It is indispensable to drive LCD's within the specified voltage limit since the higher voltage than the limit shorten LCD life. An electrochemical reaction due to direct current causes LCD deterioration, Avoid the use of direct current drive.
- Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them.

However those phenomena do not mean malfunction or out of order with LCD's which will come back in the specified operating temperature range.

- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- As light dew depositing on terminals is a cause for electro-chemical reaction resulting in

terminal open circuit.

Usage under the relative condition of 40°C, 50%RH or less is required.

(6) Storage

In the case of storing for a long period of time (for instance, for years) for the purpose or replacement use, The following ways are recommended.

- Storage in a polyethylene bag with sealed so as not to enter fresh air outside in it, And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light is.

Keeping temperature in the specified storage temperature range.

- Storing with no touch on polarizer surface by the anything else. (It is recommended to store them as they have been contained in the inner container at the time of delivery)

(7) Safety

- It is recommendable to crash damaged or unnecessary LCD into pieces and wash off liquid crystal by using solvents such as acetone and ethanol which should be burned up later.
- When any liquid crystal leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.

Hello Lighting co., ltd reserves the right to change this specification.

www.hello-lighting.com

- END -